TOSHIBA HIGH EFFICIENCY DIODE STACK (HED) SILICON EPITAXIAL TYPE

# 20JL2C41

# SWITCHING MODE POWER SUPPLY APPLICATIONS **CONVERTER & CHOPPER APPLICATION**

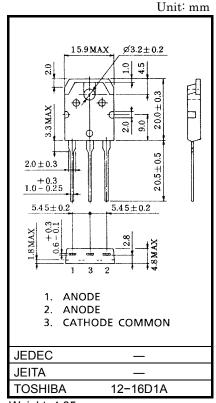
 Repetitive Peak Reverse Voltage : VRRM = 600 V Average Output Rectified Current : Io = 20 A

• Ultra Fast Reverse-Recovery Time : trr = 50 ns (Max)

Low Switching Losses and Output Noise

## ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Reverse Voltage	$V_{RRM}$	600	V	
Average Output Rectified Current	Io	20	Α	
Peak One Cycle Surge Forward	leo.	100 (50Hz)	A	
Current (Sine Wave)	IFSM	110 (60Hz)		
Junction Temparature	Tj	-40~150	°C	
Storage Temparature Range	T <sub>stg</sub>	-40~150	°C	
Screw Torque	_	0.8	N·m	



Weight: 4.85g

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

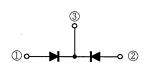
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

# **ELECTRICAL CHARACTERISTICS (Ta=25°C)**

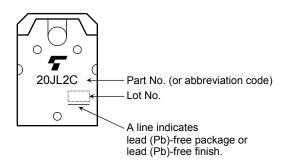
CHARACTERISTI	С	SYMBOL	TEST CONDITION	TYP.	MAX	UNIT
Peak Forward Voltage	(Note 1)	$V_{FM}$	I <sub>FM</sub> = 10A	_	2.0	V
Repetitive Peak Reverse Cu	rrent (Note 1)	I <sub>RRM</sub>	V <sub>RRM</sub> = 600V	-	50	μΑ
Reverse Recovery time	(Note 1)	t <sub>rr</sub>	I <sub>F</sub> = 2A, di / dt = - 50A / μs	_	50	ns
Forward Recovery time	(Note 1)	t <sub>fr</sub>	I <sub>F</sub> = 1A	_	150	ns
Thermal Resistance		R <sub>th (j−c)</sub>	Total DC, Junction to Case	_	1.5	°C / W

Note 1: A value applied to one cell.

#### **POLARITY**



#### **MARKING**



Abbreviation Code	Part No.		
20JL2C	20JL2C41		

### **Handling Precaution**

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

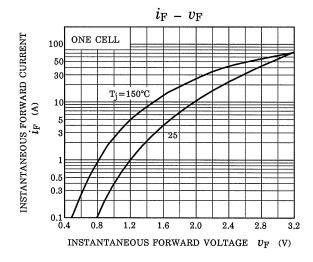
VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

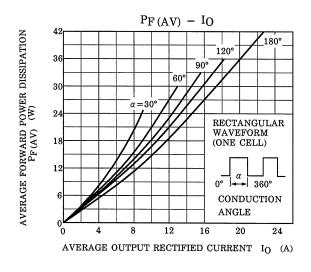
IO: We recommend that the worst case current be no greater than 80% of the absolute maximum rating of Io. Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable Tamax-Io curve.

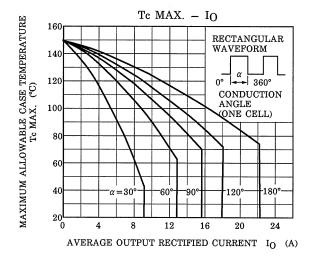
This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

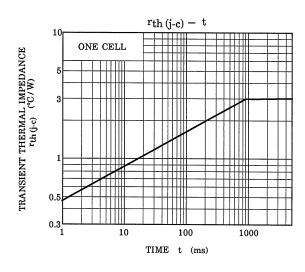
We recommend that a device be used at a Tj of below 120°C under the worst load and heat radiation conditions.

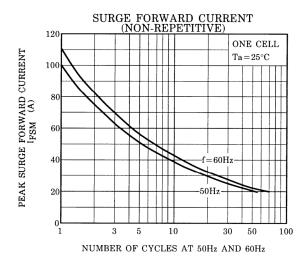
Please refer to the Rectifiers databook for further information.

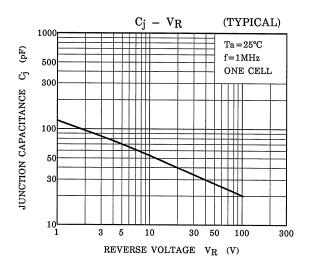












#### **RESTRICTIONS ON PRODUCT USE**

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